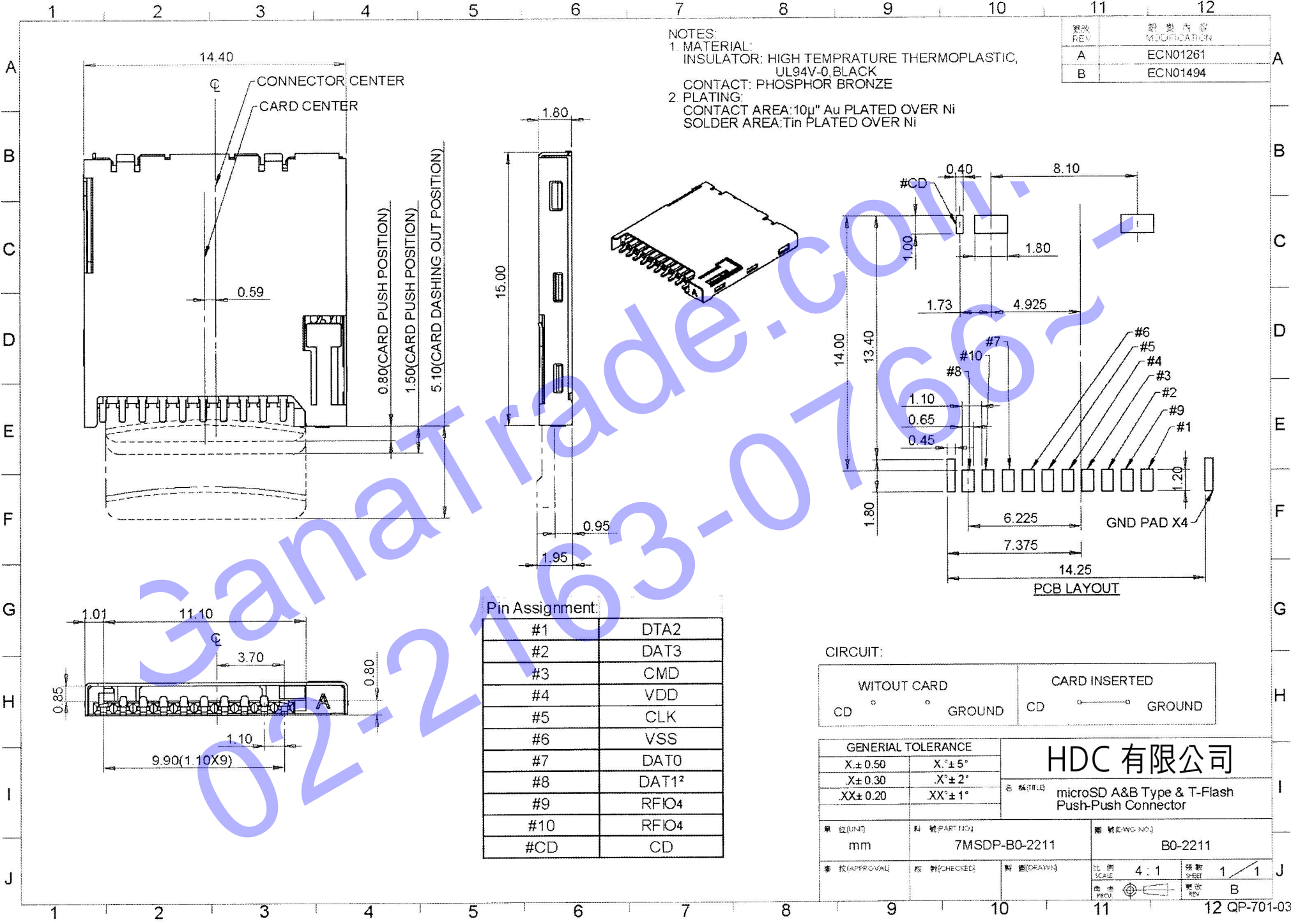


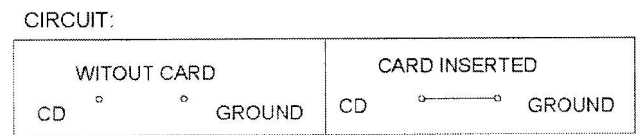
NOTES:
 1 MATERIAL:
 INSULATOR: HIGH TEMPERATURE THERMOPLASTIC,
 UL94V-0 BLACK
 CONTACT: PHOSPHOR BRONZE
 2 PLATING:
 CONTACT AREA: 10 μ " Au PLATED OVER Ni
 SOLDER AREA: Tin PLATED OVER Ni

更改 REV	變更內容 MODIFICATION
A	ECN01261
B	ECN01494



Pin Assignment:

#1	DTA2
#2	DAT3
#3	CMD
#4	VDD
#5	CLK
#6	VSS
#7	DAT0
#8	DAT1 ²
#9	RFIO4
#10	RFIO4
#CD	CD



GENERAL TOLERANCE		HDC 有限公司	
X \pm 0.50	X $^{\circ}$ \pm 5 $^{\circ}$	名稱(PLG) microSD A&B Type & T-Flash Push-Push Connector	
X \pm 0.30	X $^{\circ}$ \pm 2 $^{\circ}$		
XX \pm 0.20	XX $^{\circ}$ \pm 1 $^{\circ}$		
單位(UNIT) mm	料號(PART NO.) 7MSDP-B0-2211	圖號(DWG NO.) B0-2211	
審核(APROVAL)	校對(CHECKED)	製圖(DRAWN)	比例 SCALE 4:1 張數 SHEET 1/1
			備註(REV) B